

ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

#### Features

- Low power consumption.
- Popular T-1 diameter package.
- General purpose leads.
- Reliable and rugged.
- Long life solid state reliability.
- Available on tape and reel.
- 14V internal resistor.
- RoHS compliant.

#### T-1 (3mm) SOLID STATE LAMP

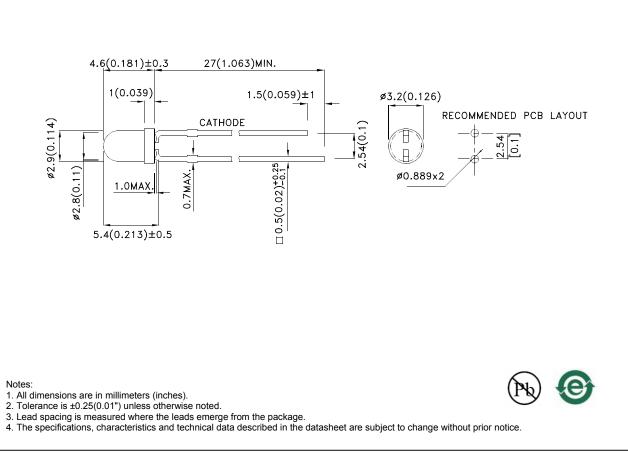
Part Number: WP710A10SGD14V

Super Bright Green

#### Descriptions

- The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

#### Package Dimensions



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#### Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] V= 14V		Viewing Angle [1]
			Min.	Тур.	201/2
WP710A10SGD14V	Super Bright Green (GaP)	Green Diffused	8	20	40°

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Green	565		nm	VF=14V
λD [1]	Dominant Wavelength	Super Bright Green	568		nm	VF=14V
Δλ1/2	Spectral Line Half-width	Super Bright Green	30		nm	VF=14V
lf	Forward Current	Super Bright Green	10.5	13.5	mA	VF=14V
IR	Reverse Current	Super Bright Green		10	uA	VR = 5V

Notes:

1. Wavelength: +/-1nm.

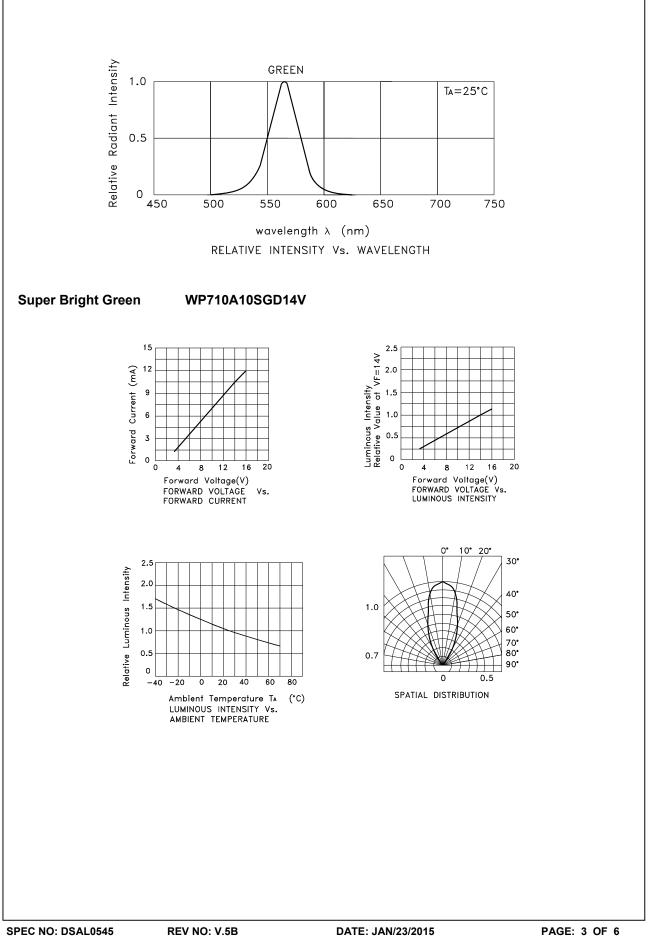
 Wavelength value is traceable to the CIE127-2007 compliant national standards.
Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

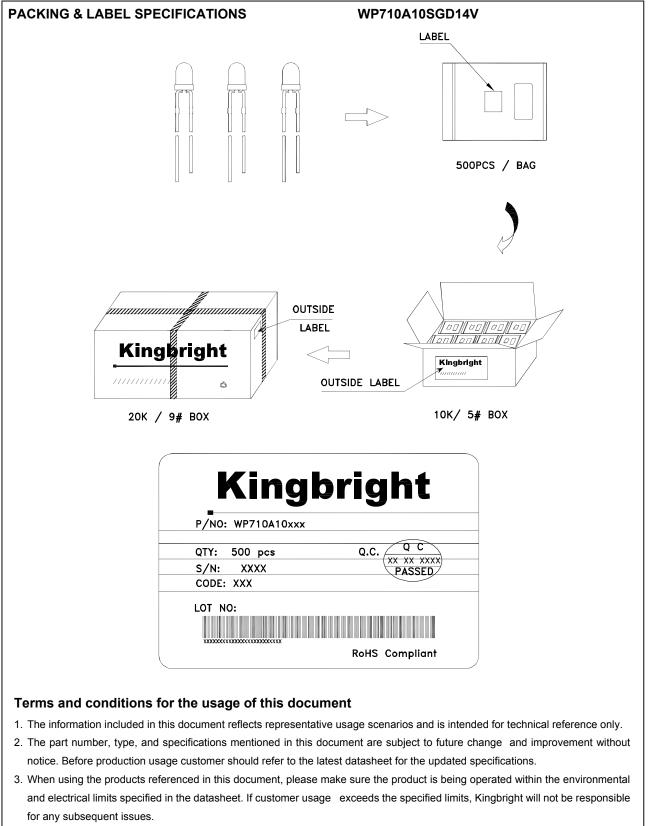
#### Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Green	Units	
Power dissipation	160	mW	
Forward Voltage	16	V	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +70°C		
Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [1]	260°C For 3 Seconds		
Lead Solder Temperature [2]	260°C For 5 Seconds		

Notes:

2. 5mm below package base.
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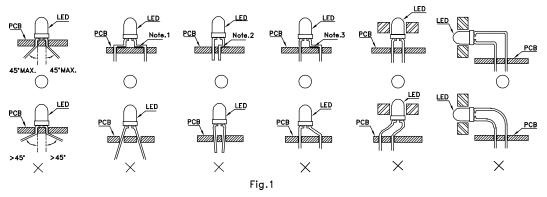


- 4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
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#### PRECAUTIONS

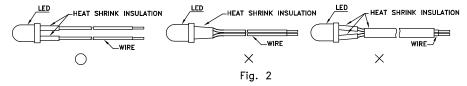
- 1. Storage conditions:
  - a.Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
  - b.LEDs should be stored with temperature  $\leq 30^{\circ}$ C and relative humidity < 60%.
  - c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.
- 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



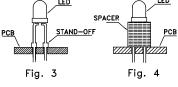
"  $\bigcirc$  " Correct mounting method "imes" Incorrect mounting method

Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

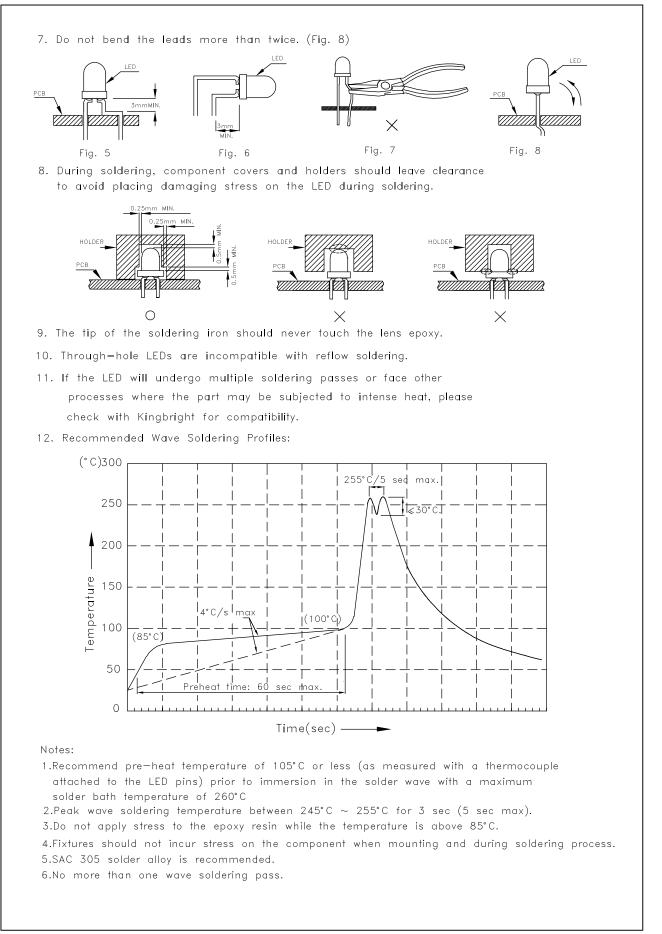
3. When soldering wires to the LED, each wire joint should be separately insulated with heat-shrink tube to prevent short-circuit contact. Do not bundle both wires in one heat shrink tube to avoid pinching the LED leads. Pinching stress on the LED leads may damage the internal structures and cause failure. (Fig. 2)



4. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 5. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 6. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)



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